

ISSUE: [August 2026](#)

The 2026 OCP Global Summit: Scaling Innovation For The AI Era

The annual [OCP Global Summit](#) is a premier event uniting the most forward-thinking minds in open IT ecosystem development. The 2026 summit, which will be held October 12-15, 2026 in San Jose, Calif., presents a unique platform for this community from around the globe to share their insights, foster partnerships and showcase cutting-edge advancements in open hardware and software. Expectations for this year's event are high in the wake of last year's astounding success, which drew nearly 11,000 attendees.

At the 2026 Global Summit, industry leaders, researchers and pioneers from the open community will engage in dynamic dialogues, enlightening workshops, and interactive engineering sessions. These activities are designed to expand our understanding of the progress that our projects have made as well as the challenges and road ahead.

Participants will explore emerging trends, tackle complex challenges and discover new opportunities to drive global innovation. Through this collaborative spirit, we aim to accelerate the development of efficient, scalable, and sustainable open compute solutions that power the future of technology.

Scaling Innovation For The AI Era

The event theme for OCP Global Summit 2026, "Scaling Innovation for the AI Era," highlights the unique perspective of the OCP community that has been pervasive throughout its 15-year history: computing at very large scale. Delivering the data center and computational infrastructure for AI is simply an extension of computing at scale that the OCP community already solves for cloud data centers.

Thus, the OCP community's model of collaboration to drive openness, efficiency, sustainability, scalability and impact will again be central to meeting the new challenges of extending data center facilities and computational systems needed to handle massively parallel and distributed AI computations at a scale that have never before been imagined.

As artificial intelligence continues to reshape industries, economies and societies, it also is reshaping data centers, redefining workloads and accelerating demand for data centers and computational infrastructure. There are enormous investments underway to build hyperscale AI data centers, with plans forming to deploy the next wave of AI: inference.

This implies AI computation is to be distributed from centralized data centers to regional data centers, to devices closer to the end user. We can expect, throughout the remainder of this decade, the demand for scalable, efficient and sustainable data center infrastructure will increase year over year.

Through its [Open Data Center Ecosystem for AI](#) vision announced in October of 2025, covering IT as well as physical data center infrastructure and facilities, the OCP community has identified the need to rethink data center technologies from chip to grid, including data center physical infrastructure and facilities, IT infrastructure, systems management and silicon supply chains. Important technology advancements include: (1) chiplet technology and associated advanced packaging, (2) subsystems such as in-rack and within data center facilities cooling and power distribution, (3) energy storage, (4) integrated telemetry for IT systems and data center facilities management (5) power generation and grid interaction, and (6) all the equipment within the data hall: AI cluster networks, storage and server architectures.

In addition, as AI inference expands to diverse hyperscale adjacent environments, creating a continuum of computation, the OCP community is working on defining open, modular infrastructure standards that scale to regional colocation, enterprise on-premises, telco points of presence and industrial sites.

This 2026 OCP Global Summit will bring together industry leaders, innovators and visionaries to share the latest advancements, forge new partnerships and define the community-developed standardizations that will scale to meet the needs of the AI-driven future. By embracing collaboration, openness and inclusivity, the OCP community is not only defining today's AI data centers, but also laying the foundation for the next wave of AI, inference.

Join us at the 2026 OCP Global Summit to collaborate, innovate and lead the future of AI and cloud data centers. This pivotal event will serve as a global nexus for driving innovation and fostering deep collaboration

throughout the expansive technology ecosystem, recognizing the transformative power of artificial intelligence across all facets of modern life, charting the course for next-generation AI data centers.

Public Registration is now open. [Click here](#) for important registration information. Tickets are limited and may sell out in advance of the show. Hotel room blocks are now available, [click here](#) to book. Questions? Contact events@opencompute.org.

OCP Conference And Expo Program

The summit features an extensive program of keynotes, breakout sessions, expo sessions and other activities spread over four days. A high level view of the programming is provided in Table 1. Within these various keynotes and sessions, the program addresses about 20 different topics, which are listed in Table 2. Among those that may be of special interest to How2Power.com readers are the tracks on DC Power Distribution, Cooling and Rack & Power.

The schedule posted on the summit website allows users to select tracks of interest. Using this feature, a list of the keynotes and power-related tracks has been generated and provided below. This list alone runs for several pages but still only represents a modest portion of a very extensive OCP program. See the website for the [Full Schedule](#).

The OCP Global Summit enjoys extensive industry support including numerous power supply and power semiconductor companies addressing data center applications. A list of this year's sponsors, as of this writing, is shown at the end of this article. For more about the summit, see the [OCP Global Summit](#) website.

Table. 2026 OCP Summit schedule at a glance.

Day 1: Monday, October 12	
Event	Time
Registration	11:00am-7:00pm
Breakout Sessions	12:00pm-3:30pm
Opening Keynotes	4:00pm-6:15pm
Opening Night Social	6:15pm-7:30pm

Meals included: evening reception hors d'oeuvres & drinks

Day 2: Tuesday, October 13	
Event	Time
Registration	7:30am-7:00pm
Keynotes	9:00am-11:15am
Expo Hall & Innovation Village	11:15am-7:00pm
Expo Hall Sessions	11:45am-5:00pm
Breakout Sessions	1:00pm-5:00pm
Booths & Bites Reception	5:00pm-7:00pm

Meals included: breakfast, lunch, afternoon snack, and evening reception hors d'oeuvres & drinks

Day 3: Wednesday, October 14	
Event	Time
Registration	7:00am-5:00pm
Breakout Sessions	8:00am-5:00pm
Future Technologies Symposium	8:00am-5:00pm
Expo Hall Sessions	9:00am-4:55pm
Expo Hall & Innovation Village	9:00am-5:00pm
Block Party	5:00pm-7:00pm

Meals included: breakfast, lunch, afternoon snack, and evening reception hors d'oeuvres & drinks

Day 4: Thursday, October 15	
Event	Time
Registration	7:00am-4:00pm
Breakout Sessions	8:00am-4:00pm
Expo Hall Sessions	8:00am-2:00pm
Expo Hall & Innovation Village	8:00am-2:00pm

Meals included: breakfast and lunch

**All times listed in Pacific Time Zone. Schedule subject to change.*

Table 2. OCP Summit tracks.

<ul style="list-style-type: none"> • Registration • Meals & Breaks • Expo Hall • Innovation Village • Keynotes • Executive Sessions • Expo Hall Sessions • Community Impact • AI Clusters • AI Computing Continuum • AI Open Data Center • AI Open DC: Power Distribution • Cooling: Cold Plate • Cooling: Immersion • Cooling Environments • Market Impact & Adoption • Networking • Open Platform Firmware (OPF) • Rack & Power • Security • Server • Server: Composable Memory Systems • Server: Open Chiplet Economy 	<ul style="list-style-type: none"> • Storage • Sustainability • Systems Management • Test & Validation • Time Appliances • OCP Special Focus: Photonics • OCP Regional Communities • Future Technologies Initiative (FTI) <ul style="list-style-type: none"> ◦ FTI Workshop: Data Centric Computing ◦ FTI Workshop: Short Reach Optical Interconnects • Future Technologies Symposium (FTS) <ul style="list-style-type: none"> ◦ FTS: Keynotes & Awards ◦ FTS: AI / HPC ◦ FTS: Data Center Sustainability ◦ FTS: Quantum (Data Center Design) • Co-located Events • IPEC Workshop • Manageability Workshop • OIF Workshop • SONiC Workshop
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2026 OCP Global Summit Keynotes And Power Related Talks

Monday, October 12, 2026

4:00 pm Welcome to the 2026 OCP Global Summit, SJCC, Street Level - South Hall, George Tchapanian - Open Compute Project Foundation (OCP)

4:15 pm AMD Keynote, SJCC, Street Level - South Hall

5:00 pm Meta Keynote, SJCC, Street Level - South Hall

5:20 pm Arm Keynote, SJCC, Street Level - South Hall, by Mohamed Awad - Arm

5:40 pm Democratizing AI Infrastructure: Accelerating Innovation at Scale, SJCC, Street Level - South Hall. Asad Khamisy - Broadcom

5:55 pm NVIDIA Keynote, SJCC - Street Level - South Hall, Ian Buck - NVIDIA

Tuesday, October 13, 2026

9:00 am OCP Welcome Address, SJCC, Street Level - South Hall, George Tchapanian - Open Compute Project Foundation (OCP)

9:15 am Microsoft Keynote, SJCC, Street Level - South Hall, Reynold D'Sa - Microsoft

9:35 am Oracle Keynote, SJCC, Street Level - South Hall, Pradeep Vincent - Oracle

9:45 am Lambda Keynote, SJCC, Street Level - South Hall

9:55 am Women in OCP Keynote, SJCC, Street Level - South Hall

10:00 am Lattice/AMI Keynote SJCC, Street Level - South Hall, Ford Tamer - Lattice Semiconductor, Sanjoy Maity - AMI

10:15 am HPE Keynote, SJCC, Street Level - South Hall, Trish Damkroger - HPE

10:30 am Intel Keynote, SJCC, Street Level - South Hall, Nic Dubé - Intel

10:50 am Power Keynotes by ABB and Eaton, SJCC, Street Level - South Hall, Rob Coyle - Open Compute Project Foundation (OCP), Paolo Catapane - ABB, Peter De Bock - Eaton

11:10 am Intelligent Infrastructure Powering the Intelligence Revolution, SJCC, Street Level - South Hall, Partha Ranganathan - Google

Wednesday, October 14, 2026

8:00 am +/-400-V / 800-V On-Board Power Delivery Requirements, SJCC, Concourse Level - 210CG. James Sun - Microsoft, Sachin Madhusoodhanan - Google, LJ LuJian - Google, Shengwen Xu - Meta, Michelle Badal - Google

8:30 am From Principles to Practice: Implementing OCP LVDC Frameworks with a 600-kW, 800-VDC Sidecar Power System Design, SJCC, Concourse Level - 210CG. Guang Yang - Siemens, Tero Järveläinen - Skeleton Technologies

8:50 am Defining End-to-End 800-VDC System Performance Requirements, SJCC, Concourse Level - 210CG, Jared Huntington - NVIDIA, Mike Tu - NVIDIA

9:10 am LVDC: Building an Open and Evolving Ecosystem, SJCC. Concourse Level - 210CG, Jason Adrian - Google, Jared Huntington - NVIDIA

9:45 am Short Circuit Bolted Fault Analysis of LVDC Power Distribution Systems for Datacenter Uses, SJCC, Concourse Level - 210CG, Sarkis Juana - UL Solutions, Dirk Mueller - UL Solutions

10:05 am 800-VDC Power Systems: Redefining Protection, Coordination & System Safety, SJCC, Concourse Level - 210CG, Manav Patel - Schneider Electric, Tony Landry - Schneider Electric

10:25 am LVDC Architecture Fundamentals: How Topology, Protection, and Standardization Define DC Power Systems, SJCC, Concourse Level - 210CG, Brian Deckard - Siemens, Giel Van den Broeck - Direct Energy Partners

10:50 am 2-Wire vs. 3-Wire at 800 VDC: Grounding, Fault Behavior, and Protection for AI Data Centers, SJCC, Concourse Level - 210CG, Lizhi Wang - Siemens, Gopal Mondal - Siemens

11:15 am Reliability, Availability, and Maintainability of High-Temperature Superconducting Power Distribution for High-Density AI Data Centers, SJCC, Concourse Level - 210CG, Bender Kutub - VEIR

12:30 pm Closing the Standards Gap for LVDC Power Distribution, SJCC, Concourse Level - 210CG, Lisa Grams - UL Solutions, Michael Jensen - UL Solutions

12:55 pm Rethinking Power Safety: The Inherent Benefits of 800-V Low Voltage DC Architectures, SJCC, Concourse Level - 210CG, Susmita Panda - Google, Satarupa Bal - Google

1:15 pm DC Arc Flash - Learnings from Practical Study and Test Results, SJCC, Concourse Level - 210CG, Tony Landry - Schneider Electric, Stuart Sheehan - Schneider Electric

1:35 pm Designing Safe 800-VDC Systems: Protection, Fault Management, and Operations, SJCC, Concourse Level - 210CG, Mike Tu - NVIDIA, Ehsan Nasr - Microsoft, Sai Somayajula - NVIDIA

2:00 pm What the Automotive Industry Can Teach Us About 800-VDC Data Centers, SJCC, Concourse Level - 210CG. Adam Morton - Flex

3:15 pm Integrating Solid State Transformer to Data Center LVDC Ecosystem, SJCC, Concourse Level - 210CG, Jing Wang - Google, Satarupa Bal - Google, Ehsan Nasr - Microsoft, Mike Tu - NVIDIA

3:40 pm Grid Interconnection Requirements for Large Loads and Path to Next-Generation Data Center Power Architectures SJCC - Concourse Level - 210CG, Sai Somayajula - NVIDIA, Amin Zamani - Danovo Energy Solutions, Mike Tu - NVIDIA, Eric Meier - ERCOT

4:05 pm Grid Requirements and Mitigation options for Large Scale AI/ML Loads, SJCC - Concourse Level - 210CG, Ashish Upreti - Google, Mike Della Penna - Google

4:25 pm Higher voltages for Direct-current Datacenters: future landscape, SJCC, Concourse Level - 210CG, Laurens Mackay - DC Opportunities, Aurelio Rodriguez Echevarria - AMD

4:45 pm The DC Fault Manager: Open Fault Coordination for 800-VDC AI Data Centers, SJCC, Concourse Level - 210CG, Ke Sun - Vertiv

Thursday, October 15, 2026

8:00 am Rack and Power (Opening and update), SJCC, Concourse Level - 230A, Steven Moore - Rittal, Harry Soin - Advanced Energy

8:20 am Open Rack Wide (ORW): Progress, Validation, and What's Next, SJCC, Concourse Level - 230A, Cecilia Galvan - Meta, Richard Banyard - Rittal

8:45 am All-in-One Rack ready for AI deployment, SJCC, Concourse Level - 230A, Zafer Cankurtaran - Rittal, Thomas Schreiner - Rittal

9:10 am Scaling Hyperscale Power Delivery: Managing Aggregated and Cascaded Power Shelf Architectures for High-Density GPU Systems, SJCC, Concourse Level - 230A, Praveen Kumar Velpuri - Microsoft, Yang Hsiung - Microsoft

9:45 am The Power Distribution sub-project at OCP - Low Voltage DC Distribution in Data Centers, SJCC, Concourse Level - 230A, Paolo Catapane - ABB, JP Buzzell - Eaton

10:05 am ORv3 Risk Assessment of Multi-degree of Freedom Transportation Vibration, SJCC, Concourse Level - 230A, Ken Leung - Google, Eric JOneson - TransPak

10:50 am High-Power-Density BBU and CBU Design for Evolving AI Data Center Power Architectures, SJCC, Concourse Level - 230A, Takuya Tsutsumi - Panasonic Corporation

11:10 am Orv3 Power architectures for Higher Power work loads, SJCC, Concourse Level - 230A, Cihan Aydin - Delta Electronics Inc., Harry Soin - Advanced Energy

12:30 pm Mitigating AI Training Power Oscillations: Utility Requirements and In-Rack Power Filtering, SJCC, Concourse Level - 230A, Bo Wen - Microsoft, Xianyong Feng - Microsoft

12:55 pm Simplifying High-Density Deployments: Reducing AC Whip Complexity in Multi-Power Shelves Open Rack Architectures, SJCC, Concourse Level - 230A, Fabricio Alves Borges - Schneider Electric, Harry Chen - Schneider Electric

1:15 pm Scaling OCP for Supercomputing: The Cray GX Infrastructure, SJCC, Concourse Level - 230A, Javier Izquierdo - HPE

1:35 pm MGX Power Rack Reference Design, SJCC, Concourse Level - 230A, Jared Huntington - NVIDIA

1:55 pm Enabling 1MW+ IT rack power with an open rack busbar interface, SJCC, Concourse Level - 230A, Hal Loket - TE Connectivity, Aniket Singh - TE Connectivity

2:15 pm 800-V direct-to-server and power shelf solutions, SJCC, Concourse Level - 230A, Harry Soin - Advanced Energy, Andy Brown - AEI - Advanced Energy

2:45 pm 800-V Data Center DC/DC Design Considerations, Topology Comparisons, and Trade-offs SJCC - Concourse Level - 230A, David Reusch - Texas Instruments

3:10 pm Applying OCP ORv3 and ORW Design Principles to Rack-Scale Arm AI Infrastructure with Supermicro, SJCC, Concourse Level - 230A, Marc Meunier - Arm, Daniel Chen - Supermicro

3:35 pm Powering the AI Rack of the Future: A Scalable 800-V DC Sidecar Architecture, SJCC, Concourse Level - 230A By Karin Tischler - Bosch Rexroth AG, Justin Mark Herrmann - Rittal

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